



Advances in Machining Process for Hard and Brittle Materials

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Deadline for manuscript
submissions:

20 June 2024

Message from the Guest Editor

Hard and brittle materials, such as semiconductors, advanced ceramics, and optical glass, are widely applied in aerospace, electronic devices, and biomedicine. Hard and brittle material machining technology is an indispensable aspect in modern manufacturing, playing a crucial role in enhancing product performance and quality. This Special Issue aims to gather the latest research on the hard and brittle material machining processes, providing new insights and prospects for academia and industry. Despite challenges encompassing material fracture, residual stresses, and subsurface damage, we possess the confidence to propel hard and brittle material machining toward a more promising future. We sincerely welcome researchers to submit innovative works related to hard and brittle material machining processes, and jointly promote the advancement and application of this field.

Keywords

hard and brittle materials; abrasive machining; laser-assisted machining; ultrasonic machining; multi-field; removal mechanism; brittle-ductile transitions; molecular dynamics; multiscale model; surface damage





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Message from the Editor-in-Chief

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